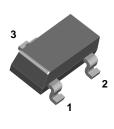
1705

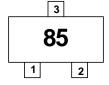


# MMBD1701/A / 1703/A / 1704/A / 1705/A



MARKING MMBD1701 85

**SOT-23** 



# 3 1703 2NC 1704

**Connection Diagrams** 

MMBD1701A 85A MMBD1703 87 MMBD1703A 87A MMBD1704 88 MMBD1704A 88A MMBD1705 89 MMBD1705A 89A

# **Small Signal Diodes**

**Absolute Maximum Ratings\*** 

T<sub>a</sub> = 25°C unless otherwise noted

Symbol	Parameter	Value	Units
$V_{RRM}$	Maximum Repetitive Reverse Voltage	30	V
I <sub>F(AV)</sub>	Average Rectified Forward Current	50	mA
I <sub>FSM</sub>	Non-repetitive Peak Forward Surge Current Pulse Width = 1.0 second	250	mA
T <sub>stg</sub>	Storage Temperature Range	-55 to +150	°C
T <sub>J</sub>	Operating Junction Temperature	150	°C

<sup>\*</sup>These ratings are limiting values above which the serviceability of any semiconductor device may be impaired.

### **Thermal Characteristics**

Symbol	Parameter	Value	Units
P <sub>D</sub>	Power Dissipation	350	mW
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient	357	°C/W

### Electrical Characteristics T<sub>A</sub> = 25°C unless otherwise noted

Symbol	Parameter	Test Conditions	Min	Max	Units
$V_R$	Breakdown Voltage	I <sub>R</sub> = 5.0 μA	30		V
V <sub>F</sub>	Forward Voltage	$I_F = 10 \mu A$ $I_F = 100 \mu A$ $I_F = 1.0 mA$ $I_F = 10 mA$ $I_F = 20 mA$ $I_F = 50 mA$	420 520 640 760 810 0.89	500 610 740 880 950 1.1	mV mV mV mV
I <sub>R</sub>	Reverse Current	V <sub>R</sub> = 20 V		50	nA
Ст	Total Capacitance	V <sub>R</sub> = 0, f = 1.0 MHz		1.0	pF
t <sub>rr</sub>	Reverse Recovery Time  MMBD1701-1705	$I_F = I_R = 10 \text{ mA}, I_{RR} = 1.0 \text{ mA},$ $R_L = 100 \Omega$		0.7	ns
	MMBD1701A-1705A	$I_F = I_R = 10 \text{ mA}, I_{RR} = 1.0 \text{ mA},$ $R_L = 100 \Omega$		1.0	ns

<sup>1)</sup> These ratings are based on a maximum junction temperature of 150 degrees C.
2) These are steady state limits. The factory should be consulted on applications involving pulsed or low duty cycle operations

# **Small Signal Diode**

(continued)

## **Typical Characteristics**

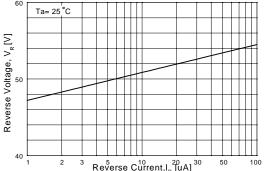


Figure 1. Reverse Voltage vs Reverse Current BV - 1.0 to 100 uA

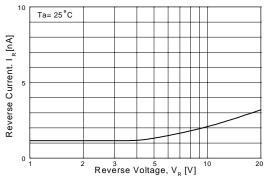


Figure 2. Reverse Current vs Reverse Voltage IR - 1 to 22V

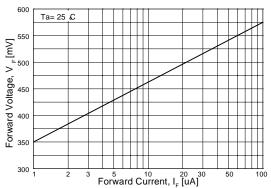


Figure 3. Forward Voltage vs Forward Current VF - 1.0 to 100 uA

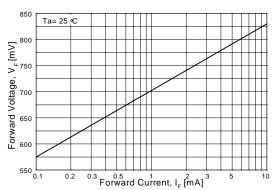


Figure 4. Forward Voltage vs Forward Current VF - 0.1 to 10 mA

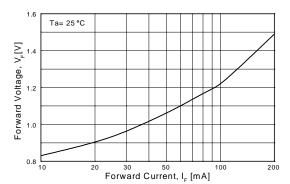


Figure 5. Forward Voltage vs Forward Current VF - 10 - 200 mA

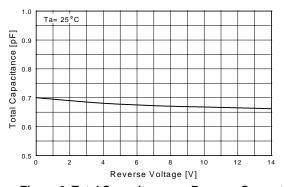


Figure 6. Total Capacitance vs Reverse Current

# **Small Signal Diode**

(continued)

# Typical Characteristics (continued)

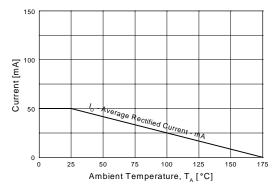


Figure 7. Average Rectified Current  $(I_o)$  versus Ambient Temperature  $(T_A)$ 

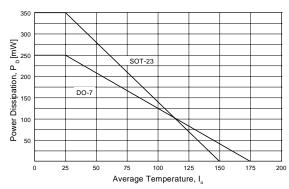


Figure 8. Power Derating Curve

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